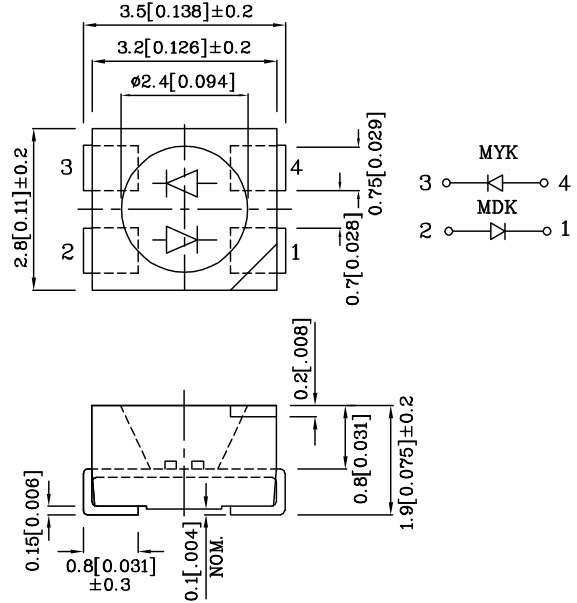


Features

- BOTH CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 1500PCS / REEL.
- RoHS COMPLIANT.



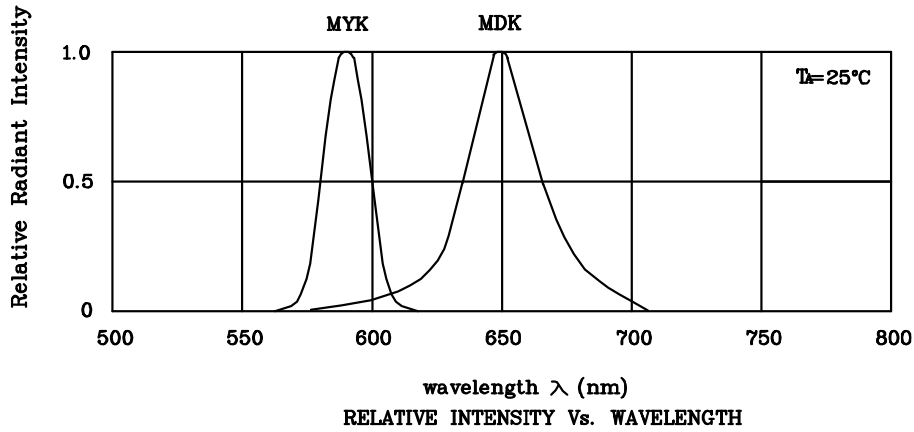
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

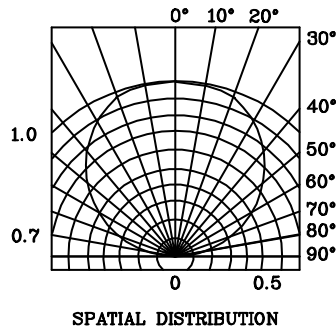
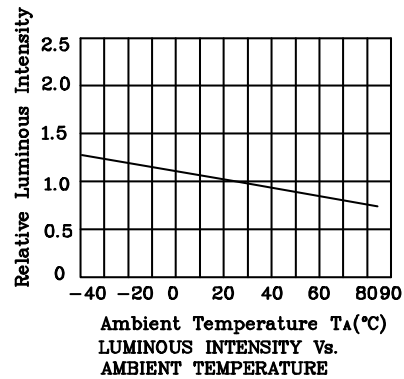
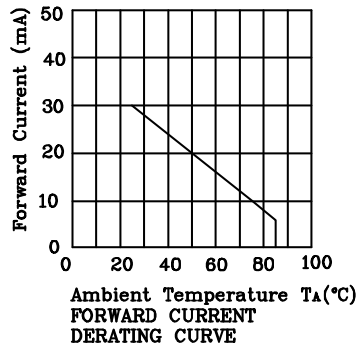
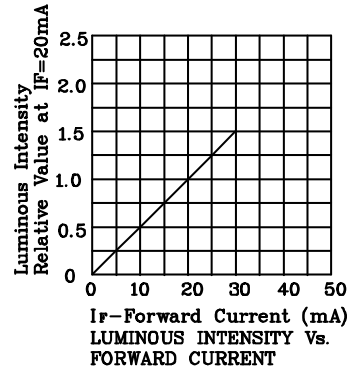
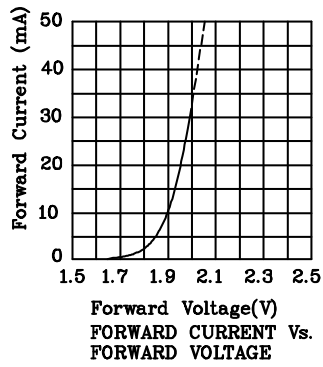
Absolute maximum ratings ($T_A=25^\circ\text{C}$)		MDK (InGaAl P)	MYK (InGaAl P)	Unit
Reverse Voltage	V_R	5	5	V
Forward Current	I_F	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	185	175	mA
Power Dissipation	P_T	75	75	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	T_{stg}	-40 ~ +85		

Operating Characteristics ($T_A=25^\circ\text{C}$)		MDK (InGaAl P)	MYK (InGaAl P)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	1.95	2.0	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	2.5	V
Reverse Current ($V_R=5\text{V}$)	I_R	10	10	μA
Wavelength of Peak Emission ($I_F=20\text{mA}$)	λ_P	650	590	nm
Wavelength of Dominant Emission ($I_F=20\text{mA}$)	λ_D	635	590	nm
Spectral Line Full Width At Half-Maximum ($I_F=20\text{mA}$)	$\Delta\lambda$	28	20	nm
Capacitance ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	35	20	pF

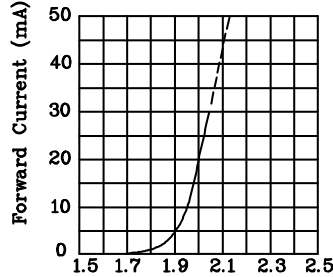
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$)		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XZMDKMYK45W	Red	InGaAlP	Water Clear	70	198	650	120°
	Yellow	InGaAlP		18	98	590	



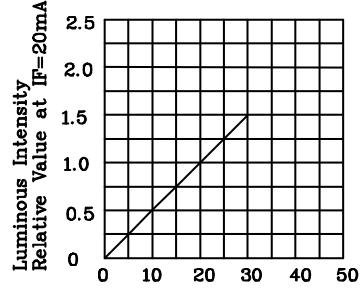
❖ MDK



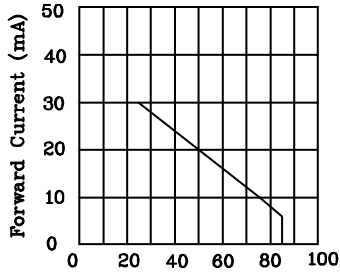
❖ MYK



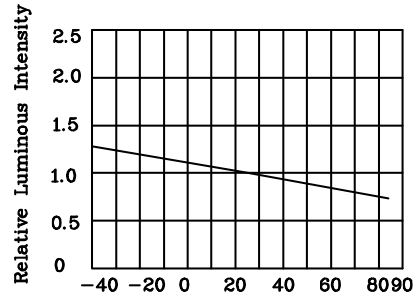
Forward Voltage(V)
**FORWARD CURRENT Vs.
 FORWARD VOLTAGE**



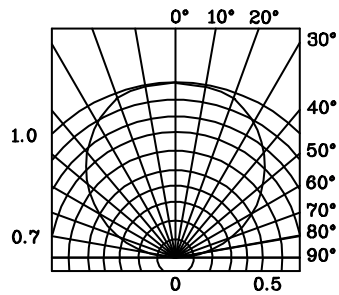
I_F -Forward Current (mA)
**LUMINOUS INTENSITY Vs.
 FORWARD CURRENT**



Ambient Temperature T_A (°C)
**FORWARD CURRENT
 DERATING CURVE**

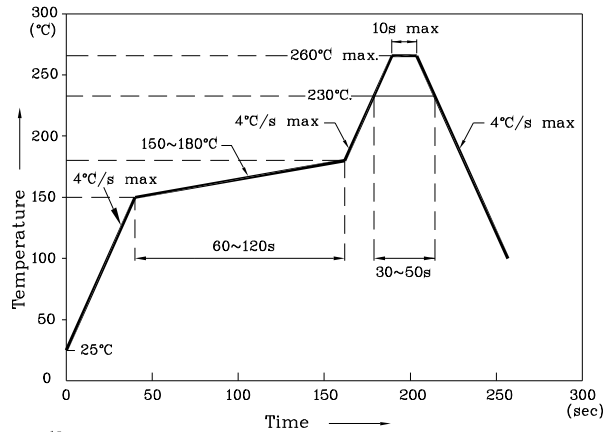


Ambient Temperature T_A (°C)
**LUMINOUS INTENSITY Vs.
 AMBIENT TEMPERATURE**



SPATIAL DISTRIBUTION

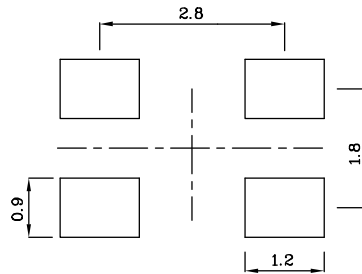
Reflow Soldering Profile For Lead-free SMT Process.



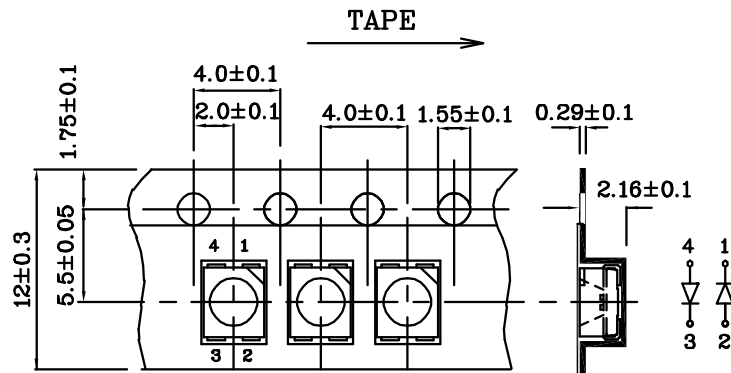
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.1)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.